



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

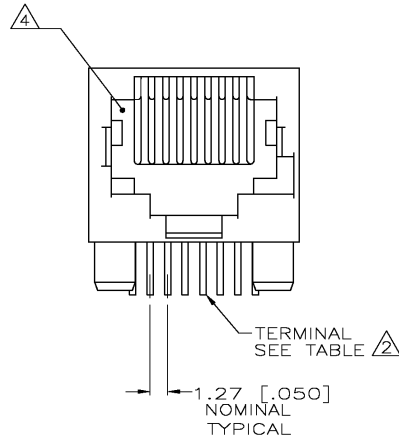
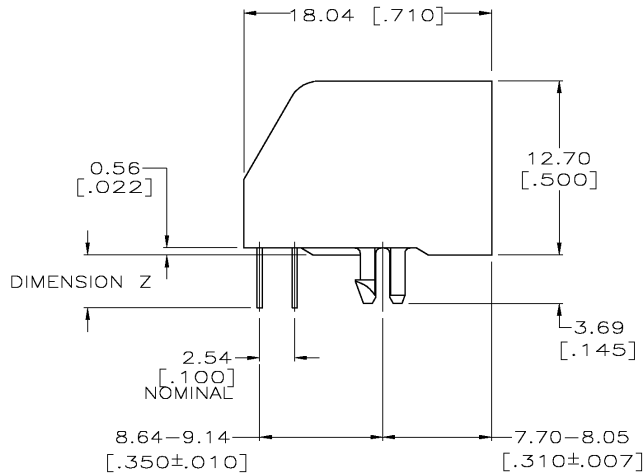
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

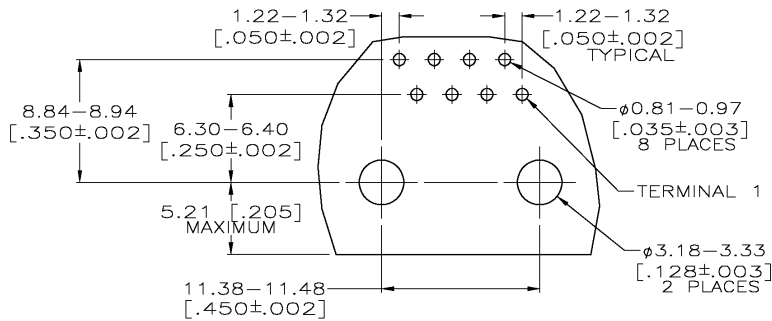
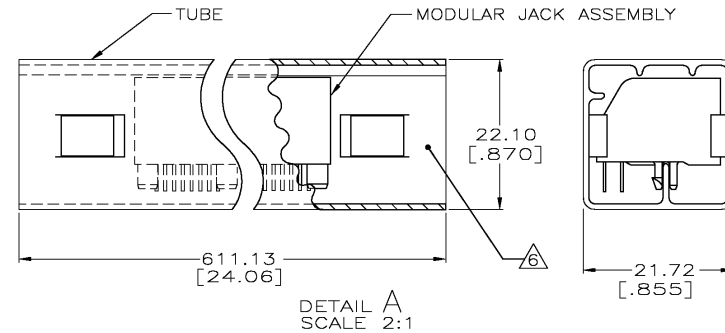
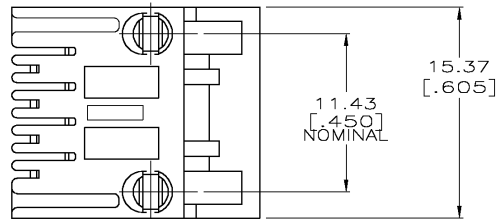


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DRAWING MADE IN THIRD ANGLE PROJECTION
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LOC		DIST		REVISIONS				DATE	APPO
P	F	ZONE	LTR	DESCRIPTION					
GP	00			H	REVISED PER EC 0511-0016-04		27JAN04	JB	



- △ DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- △ TERMINALS FOR 555167-2 LOCATED IN CENTER POSITIONS.
- △ MATERIAL: HOUSING - PBT POLYESTER, BLACK.
TERMINAL - PHOS-BRONZE PLATED WITH 1.27µm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03µm [.000080] THICK TIN LEAD IN SOLDER AREA OVER 1.27µm [.000050] THICK NICKEL UNDERPLATE.
- △ CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ BULK PACKAGED IN A TRAY.
- △ PACKAGED 36 ASSEMBLIES PER TUBE WITH BOTH ENDS CRIMPED. SEE DETAIL A.



SUGGESTED PRINTED CIRCUIT BOARD
MOUNTING HOLE LAYOUT
LAYOUT SHOWN FROM CIRCUIT SIDE OF BOARD

SUPERSEDED BY 555167-1

	PACKAGED	TERMINALS	DIMENSION Z	PART NUMBER
△	8	2.80±0.25 [.110±.010]		555167-4
	8	3.81±0.51 [.15±.02]		555167-3
△	6	3.81±0.51 [.15±.02]		555167-2
	8	3.81±0.51 [.15±.02]		555167-1

DO NOT SCALE PRINT. UNLESS SPECIFIED DIMENSIONS IN mm [INCHES] TOLERANCES ON :	DR 11-16-93 B. SIMPSON	AMP Incorporated Harrisburg, PA 17105-3608
2 PLC DEC ± -	CHK 11-17-93 C. WHITT	
3 PLC DEC ± -	APPD 11-22-93 J. TONEY	
ANGLES ± -	APPD 11-22-93 H. MCGRATH	
MATERIAL	PRODUCT SPEC 108-1163	NAME MODULAR JACK ASSEMBLY 8 POSITION, LOW PROFILE, RIGHT ANGLE, KEYED, WITHOUT PANEL STOPS
FINISH	APPLICATION SPEC 114-2048	SIZE C
	WEIGHT -	CAGE CODE 00779
		DRAWING NO 555167
		SCALE 4:1
		SHEET 10F 1

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